

LTM8033 76LD-BGA-PBF 15mm X 11.25mm X 4.92mm -SOLDER DA(TABLE OF MATERIAL DECLARATION)											
The LTM8033 is RoHS compliant per EU RoHS Directive 2003/95/EC.											
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)											
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)				
1	Substrate	Circuit Board	0.1868	Barium Compounds	7727-43-7	0.00469	2.510				
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2, non-disclosure	0.03562	19.070				
				Copper Metal	7440-50-8	0.10599	56.750				
				Copper Compounds	147-14-8	0.00004	0.022				
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00002	0.010				
				Gold metal or alloy	7440-57-5	0.00032	0.170				
				Nickel	7440-02-0	0.00151	0.810				
				Zinc	7440-66-6	0.00021	0.110				
				Continuous Filament Fiber Glass	65997-17-3	0.02798	14.980				
				Acrylic Resin	non-disclosure	0.00893	4.780				
				Epoxy Resin	non-disclosure	0.00003	0.016				
				Chromium(III) Oxide	1308-38-9	0.00001	0.004				
				Silica Amorphous	7631-86-9	0.00010	0.051				
				Talc;not containing fiber like asbestos	14807-96-6	0.00054	0.290				
				Aromatic carbonyl compounds	non-disclosure	0.00050	0.270				
				Cyanoguanidine	461-58-5	0.00001	0.008				
				Calcium caobonate	471-34-1	0.00056	0.003				
				Amine compounds	non-disclosure	0.00007	0.037				
				Leveling agent and others	non-disclosure	0.00021	0.110				
				2	Solder Paste	Alloy	0.2145	Sn	7440-31-5	0.20375	95.000
								Sb	7440-36-0	0.01072	5.000
3	Passive/Active Components		0.7208	Iron Powder (Fe)	7439-89-6	0.46874	65.03				
				Copper (Cu)	7440-50-8	0.15429	21.40				
				Nickel (Ni)	7440-02-0	0.01159	1.61				
				Tin (Sn)	7440-31-5	0.00689	0.96				
				Ceramic (Ba) Compounds	12047-27-7	0.07928	11.00				
4	Active Ics	Silicon	0.0039	Silicon	7440-21-3	0.00394	100.000				
5	Wire	Gold	0.0024	Au	7440-57-5	0.00240	99.990				
6	Solder Ball	SAC305	0.1279	Sn	7440-31-5	0.12342	96.50				
				Ag	7440-22-4	0.00384	3.00				
				Cu	7440-50-8	0.00064	0.50				
7	Encapsulation	Epoxy Resin	1.0187	Fused Silica	60676-86-0	0.78647	77.200				
				Epoxy Resin	non-disclosure	0.09067	8.900				
				Phenol Resin	non-disclosure	0.09067	8.900				
				Crytalline Silica	14808-60-7	0.03056	3.000				
				Carbon Black	1333-86-4	0.00509	0.500				
				Metal Hydroxide	non-disclosure	0.01528	1.500				
Total Package Weight			2.2750								

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts